FORM PTO-144 (REV.7-80)	9 ,	U P.	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. 501317.02 (30302/US)		APPLICATION NO. 10/691,020				
INFORMATION DISCLOSURE STATEMENT					APPLICANT(S) Philip Neaves and Andrew Lever						
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*EXAMINER INITIAL	(4) E	DOCUMENT NUMBER	DATE	NAME		CLASS		SUBCLASS	FILING DATE IF APPROPRIATE		
m	АА	3,782,504	01/01/74	Billmaier et al.		187		29 R			
m	AB	4,280,221	07/21/81	Chun et al.		375 17		17			
7	AC	5,974,464	10/26/99	Shin et al.		709 231		231			
TW	AD	6,690,309 B1	02/10/04	James et al.		341		102			
n	AE	6,859,883 B2	02/22/05	Svestka et al.		713 320		320			
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FORM PTO-1449 (REV.7-80)

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

INFORMATION DISCLOSURE STATEMENT (Use several sheets if necessary)

ATTY, DOCKET NO. 501317.02 (30302/US) APPLICATION NO. Not Yet Assigned

APPLICANT(S)

Philip Neaves and Andrew Lever

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•EXAMINER		DOCUMENT NUMBER	DATE		NAME	CLASS SUBCE		FILING DATE		
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				Sheet <u>2</u> of <u>2</u>					
FORM PTO-1449 (REV.7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 501317.02 (30302/US)	APPLICATION NO. 10/691,020					
INFORMATION DISCLOSURE STATEMENT		ATION DISCLOSURE STATEMENT	APPLICANT(S) Philip Neaves and Andrew Lever						
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TN	"International Technology Roadmap for Semiconductors", Assembly and Packaging, 2001, aw pp. 1-21.								
M	AX	Karnezos, M. et al., "System in a Package (SiP) Benefits and Technical Issues", in <i>Proceedings</i> of APEX, San Diego, California, 2002, 7 pages.							
m	AY	Mick, S. et al., "4Gbps High-Density AC Coupled Interconnection", Department of Electrical and Computer Engineering North Carolina State University, IEEE Custom Integrated Circuits Conference, May 12-16, 2002, pp. 133-140.							
7	ΑZ	"Rapidly Advancing System-in-Package Fabrication Technology", Vol. 20, No.3, 2002, pp. 3-11.							
:7~	ВА	Scanlan, C.M. et al., "System-In-Package Technology, Application and Trends", 2001 Proceedings of SMTA International, Rosemont, Illinois, pp. 764-773.							
7	вв	Wang, M. et al., "Configurable Area-IO Memory for System-In-A-Package (SiP)", 27 th European Solid-State Circuits Conference, September, 2001, 4 pages.							
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M	ΑВ	5,818,112	10/06/98	Weber et	257		777			
Th	ΛС	6,496,889 B1	12/17/02	Perino et	Perino et al.			110		
TW	AD	6,500,696 B2	12/31/02	Sutherland				109		
The	AE	2001/0039075 A1	11/08/01	Doyle et a	ıl.	438		107		
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